

General Description

The Sanrise SRT10N070H is a low voltage power MOSFET, fabricated using advanced split gate trench technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and synchronous rectification.

The SRT10N070H break down voltage is 100V and it has a high rugged avalanche characteristics. The SRT10N070H is available in PDFN5*6 and TO-220C packages.

Features

- Ultra Low
- $R_{DS(ON_TYP)} = 5.7m\Omega$,PDFN5*6 @ $V_{GS} = 10V$.
- $R_{DS(ON_TYP)} = 6.3m\Omega$,TO-220C @ $V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g = 32.1nC$ typ.
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified

Application

- Charger / Adapter
- Server/Telecom
- High Power Supply
- E-Tools

Ordering Information

Symbol

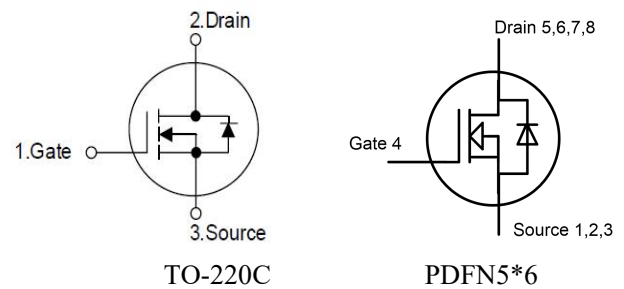


Figure 1 Symbol of SRT10N070H

Package Type

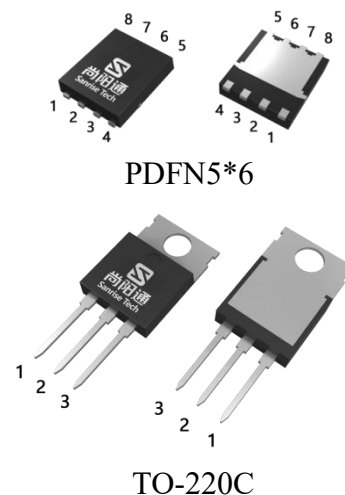
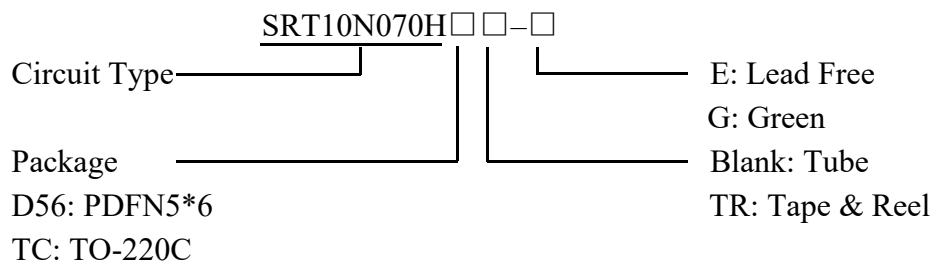


Figure 2 Package Type of SRT10N070H



Package	Part Number	Marking ID	Packing Type
PDFN5*6	SRT10N070HD56TR-G	SRT10N070HD56G	Tape & Reel
TO-220C	SRT10N070HTC-G	SRT10N070HTCG	Tube

7mΩ, 100V, N-Channel Power MOSFET
SRT10N070H
Absolute Maximum Ratings

Parameter		Symbol	Rating		Unit
Drain-Source Voltage		V _{DSS}	100		V
Gate-Source Voltage		V _{GSS}	±20		V
Continuous Drain Current	T _C =25°C	I _D	PDFN5*6	84	A
	T _C =100°C		TO-220C	87	
			PDFN5*6	53	
			TO-220C	56	
Pulsed Drain Current (Note 2)		I _{DM}	336		A
Avalanche Energy, Single Pulse (Note 3)		E _{AS}	36		mJ
Avalanche Destructive Energy, Single Pulse (Note 4)		E _{AS_Limit}	306		mJ
Avalanche Energy, Repetitive (Note 2)		E _{AR}	0.05		mJ
Avalanche Current, Repetitive (Note 2)		I _{AR}	12		A
Continuous Diode Forward Current		I _S	84		A
Diode Pulse Current		I _{S.PULSE}	320		A
Max Power Dissipation		P _D	96.1		W
Operating Junction Temperature		T _J	150		°C
Storage Temperature		T _{STG}	-55 to 150		°C
Lead Temperature (Soldering, 10 sec)		T _{LEAD}	260		°C

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. $I_{AS}=12.0\text{A}$, $V_{DD}=50\text{V}$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$
4. $I_{AS_Limit}=35\text{A}$, $V_{DD}=50\text{V}$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$

Thermal Resistance

Parameter		Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	PDFN5*6	R_{thJC}			1.3	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient		R_{thJA}			50	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	TO-220C	R_{thJC}			1.1	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient		R_{thJA}			60	$^{\circ}\text{C}/\text{W}$

7mΩ, 100V, N-Channel Power MOSFET
SRT10N070H
Electrical Characteristics
 $T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter		Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics							
Drain-Source Breakdown Voltage		BV _{DSS}	V _{GS} =0V, I _D =250uA	100			V
Zero Gate Voltage Drain Current		I _{DSS}	V _{DS} =100V, V _{GS} =0V			1	uA
Gate-Body Leakage Current	Forward	I _{GSSF}	V _{GS} =20V, V _{DS} =0V			100	nA
	Reverse	I _{GSSR}	V _{GS} =-20V, V _{DS} =0V			-100	
Gate Threshold Voltage		V _{GS(TH)}	V _{DS} =V _{GS} , I _D =0.25mA	2.0	3.0	4.0	V
Static Drain-Source On-Resistance	PDFN5*6	R _{DS(ON)}	V _{GS} =10V, I _D =14A		5.7	7.0	mΩ
	TO-220C		V _{GS} =10V, I _D =14A		6.3	7.5	
Gate Resistance		R _G	f=1MHz, Open Drain		1.7		Ω
Dynamic Characteristics							
Input Capacitance		C _{ISS}	V _{DS} =50V, V _{GS} =0V, f=1MHz		2.1		nF
Output Capacitance		C _{OSS}			720		pF
Reverse Transfer Capacitance		C _{RSS}			13		pF
Effective output capacitance, energy related ^{NOTE5}		C _{O(er)}	V _{GS} =0V, V _{DS} =0...80V		690		pF
Effective output capacitance, time related ^{NOTE6}		C _{O(tr)}			920		
Turn-on Delay Time		t _{d(on)}	V _{DD} =50V, I _D =30A R _G =3.0Ω, V _{GS} =10V		10		nS
Rise Time		t _r			5		
Turn-off Delay Time		t _{d(off)}			22		
Fall Time		t _f			6		
Gate Charge Characteristics							
Gate to Source Charge		Q _{gs}	V _{DD} =50V, I _D =30A V _{GS} =0 to 10.0V		9.7		nC
Gate to Drain Charge		Q _{gd}			6.2		
Gate Charge Total		Q _g			32.1		
Gate Plateau Voltage		V _{plateau}			4.6		V
Gate Charge Total, sync FET		Q _g	V _{DD} =0.1V, V _{GS} =0 to 10V		27.6		nC
Reverse Diode Characteristics							
Drain-Source Diode Forward Voltage		V _{SD}	V _{GS} =0V, I _{SD} =30A		0.85	1.1	V
Reverse Recovery Time		t _{rr}	V _R =50V, I _F =30A dI _F /dt=100A/us		53		nS
Reverse Recovery Charge		Q _{rr}			93		nC
Peak Reverse Recovery Current		I _{rrm}			3.5		A

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 80V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 80 V

Typical Performance Characteristics

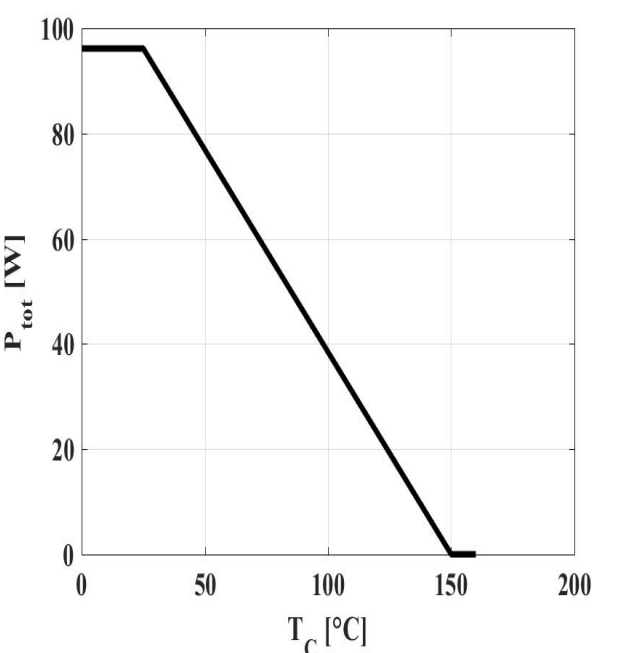
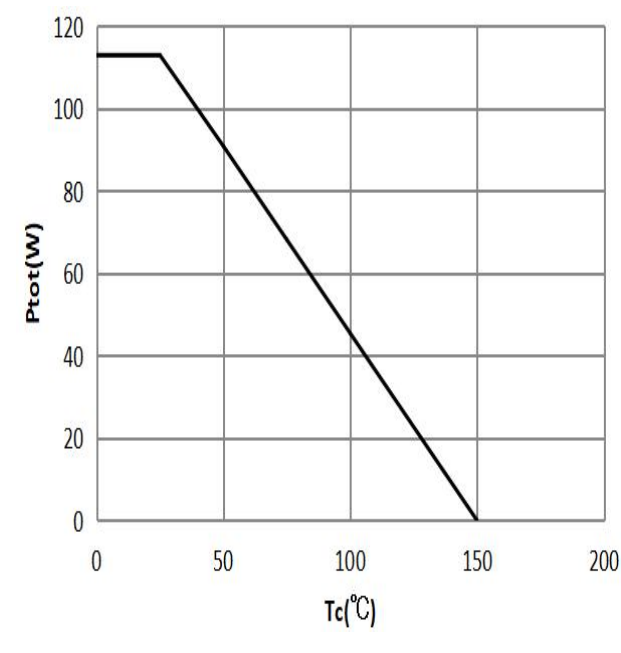
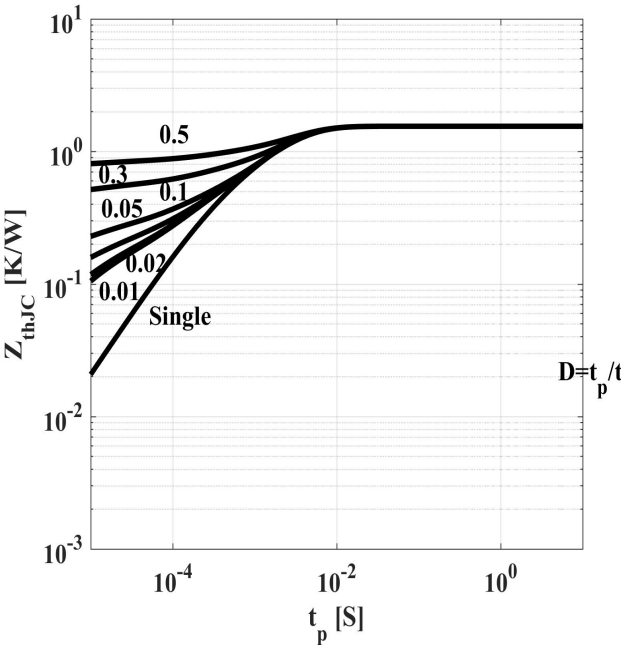
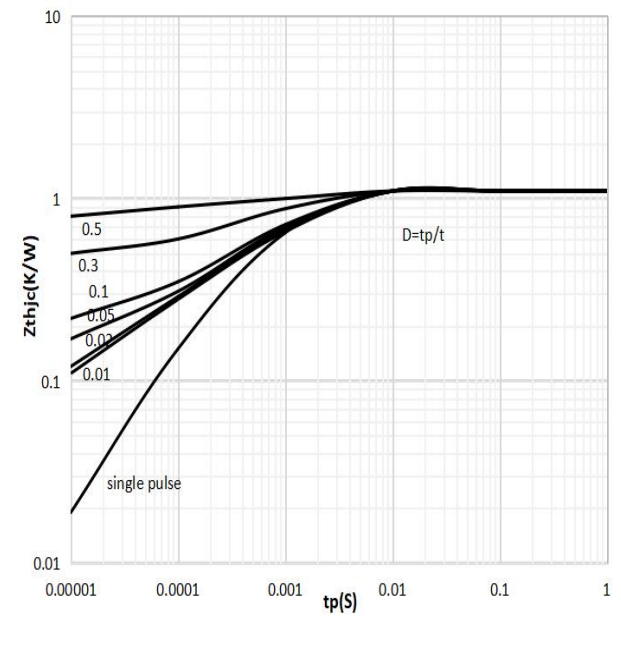
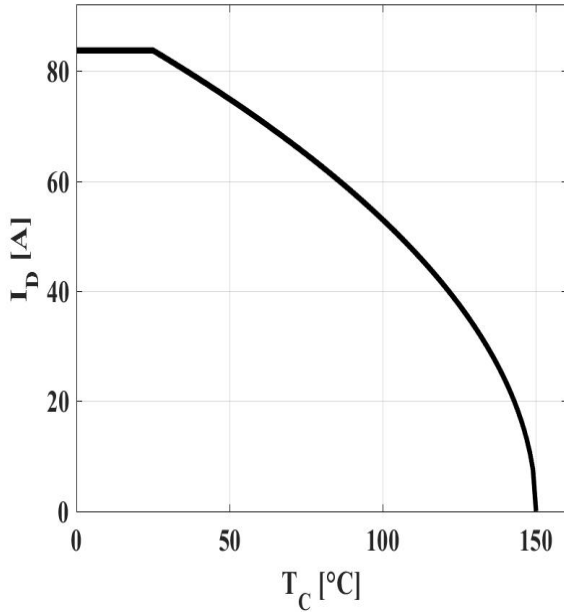
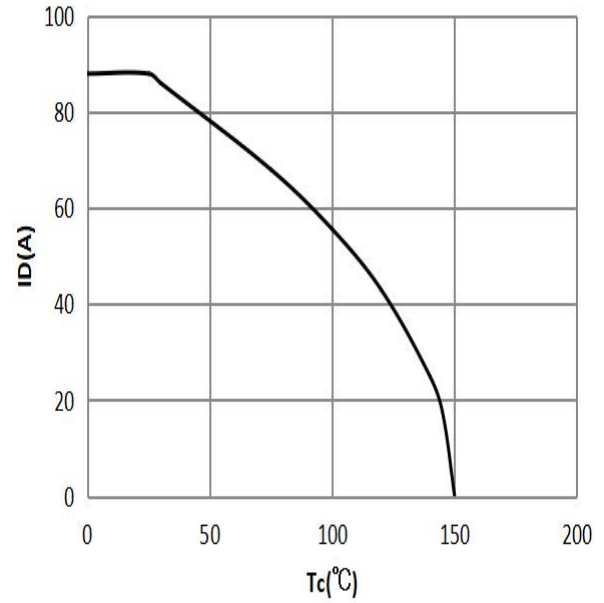
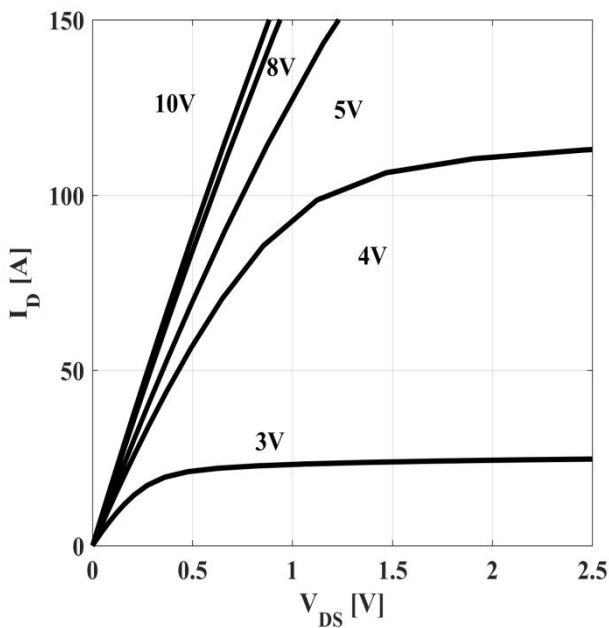
Figure 3A: Power Dissipation (PDFN5*6)  $P_{tot}=f(T_c)$	Figure 3B: Power Dissipation (TO-220C)  $P_{tot}=f(T_c)$
Figure 4A: Max. Transient Thermal Impedance (PDFN5*6)  $Z_{(thJC)}=f(t_p)$;parameter:$D=t_p/T$	Figure 4B: Max. Transient Thermal Impedance (TO-220C)  $Z_{(thJC)}=f(t_p)$;parameter:$D=t_p/T$

Figure5A: Drain Current(PDFN5*6)


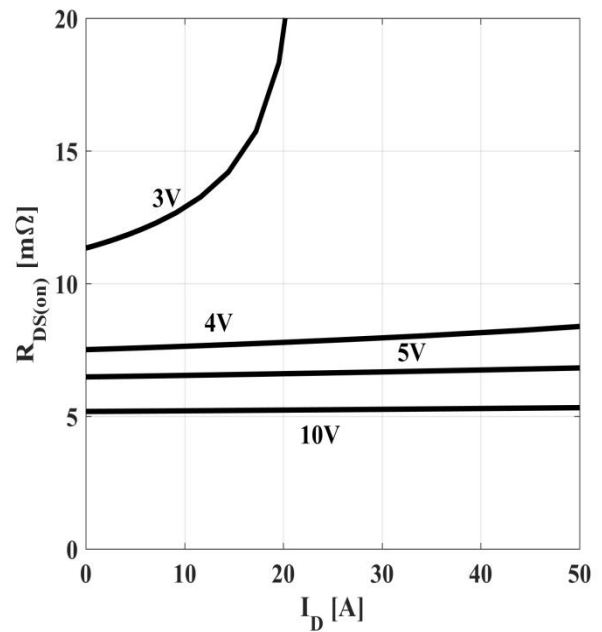
$$I_D = f(T_c); V_{GS} \geq 10V$$

Figure5B: Drain Current(TO-220C)


$$I_D = f(T_c); V_{GS} \geq 10V$$

Figure6: Typ. Output Characteristics


$$I_D = f(V_{DS}); T_j = 25^\circ C; \text{parameter: } V_{GS}$$

Figure7: Typ. Drain-Source On-State Resistance


$$R_{DS(ON)} = f(I_D); T_j = 25^\circ C; \text{parameter: } V_{GS}$$

7mΩ, 100V, N-Channel Power MOSFET
SRT10N070H

Figure8: Typ. Transfer Characteristics

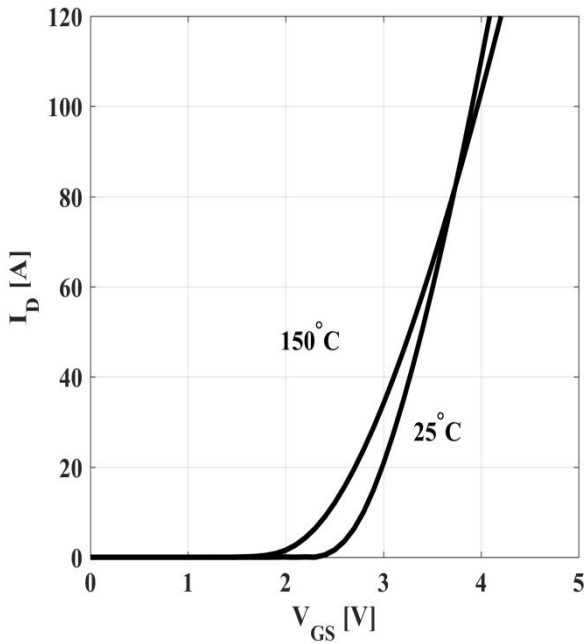

 $I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}; \text{parameter: } T_j$

Figure9: Typ. Forward Transconductance

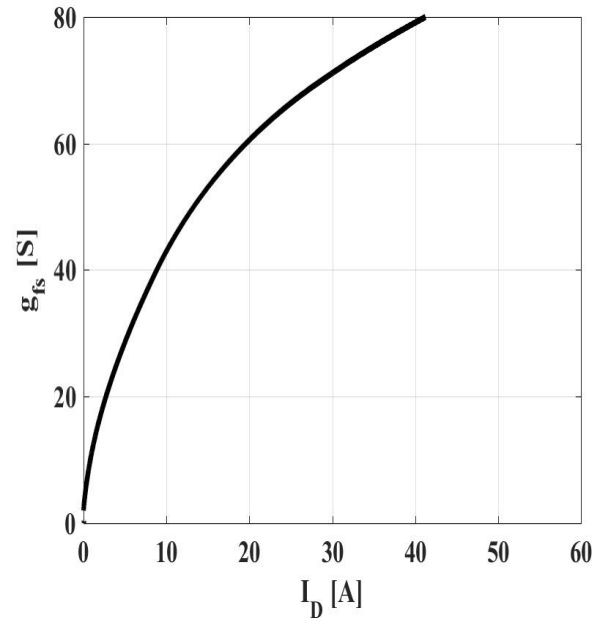

 $g_{fs} = f(I_D); T_j = 25^\circ\text{C}$

Figure10A: Typ. Drain-Source On-State Resistance(PDFN5*6)

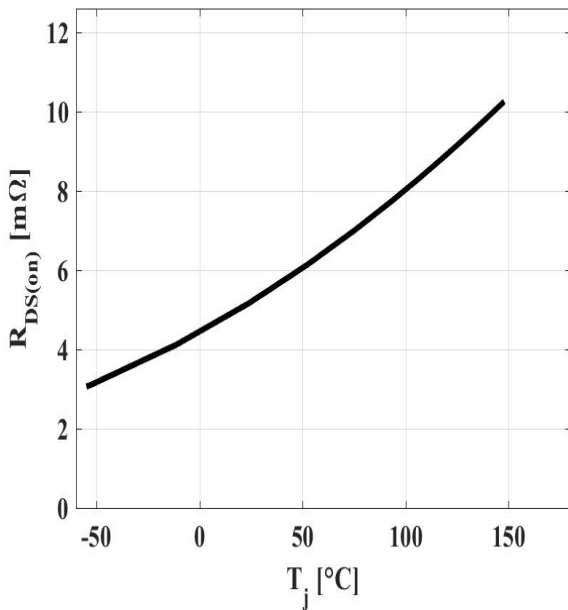

 $R_{DS(ON)} = f(T_j); I_D = 14\text{A}; V_{GS} = 10\text{V}$

Figure10: Typ. Drain-Source On-State Resistance (TO-220C)

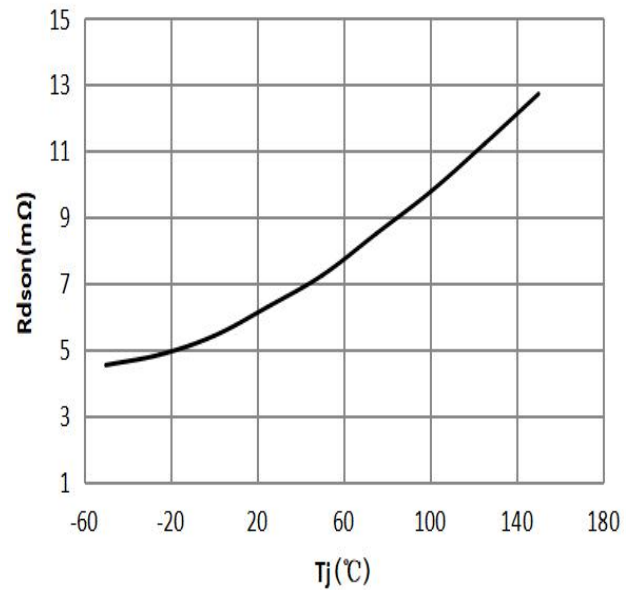
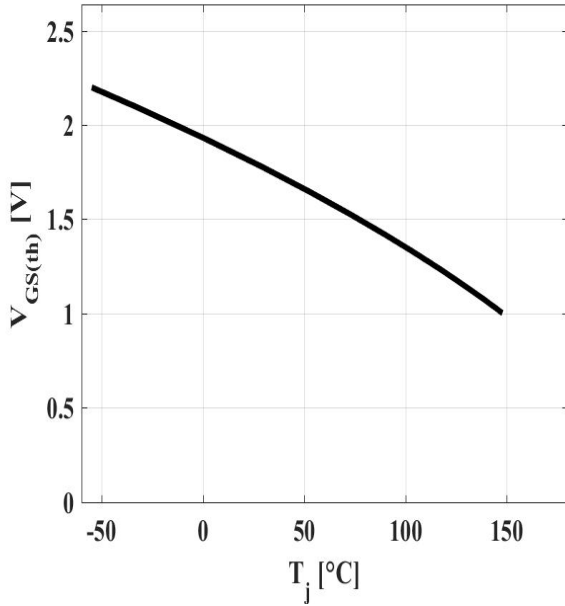
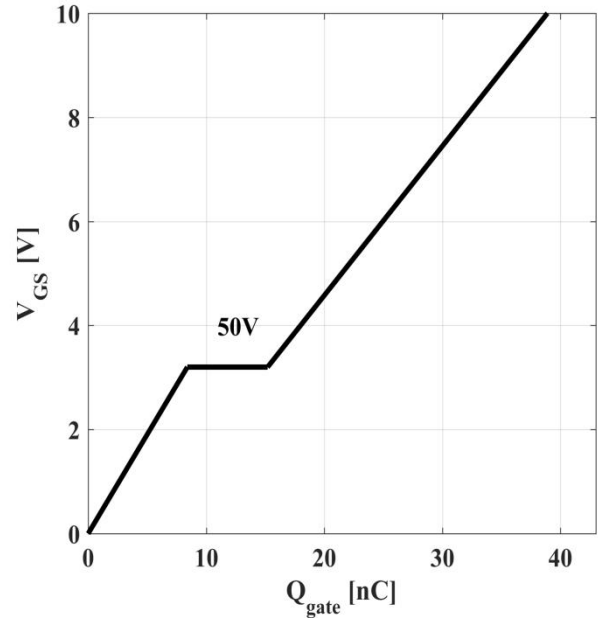
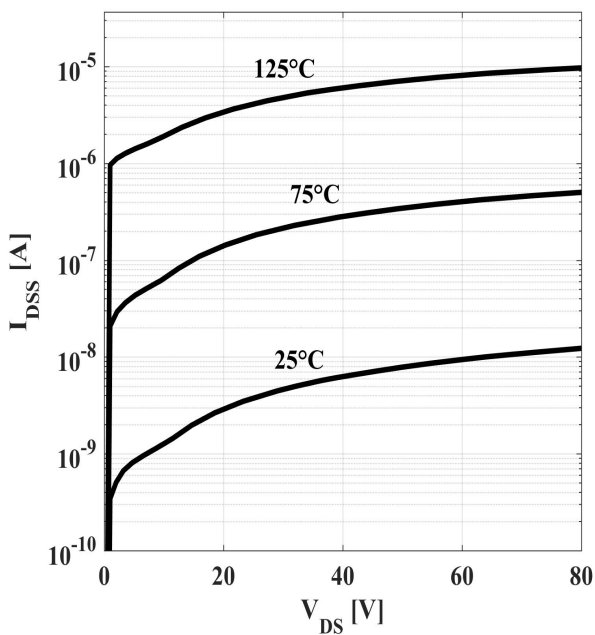

 $R_{DS(ON)} = f(T_j); I_D = 14\text{A}; V_{GS} = 10\text{V}$

Figure 11: Typ. Gate Threshold Voltage


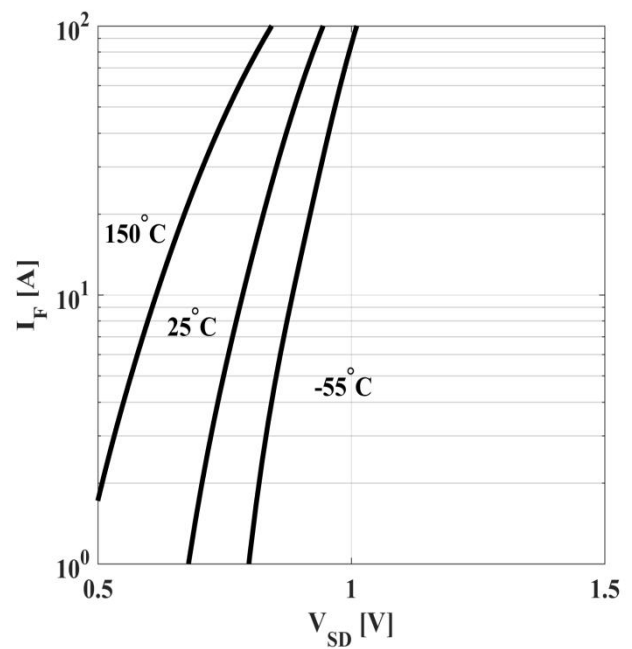
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}; I_{DS} = 250\mu A$$

Figure 12: Typ. Gate Charge


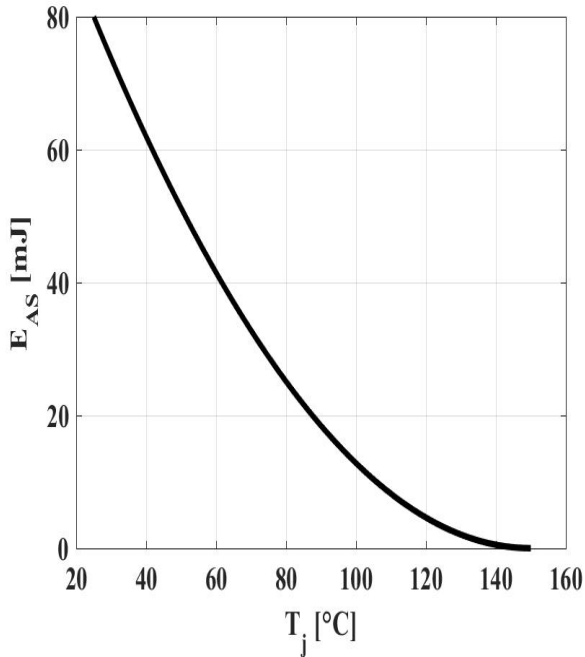
$$V_{GS} = f(Q_{gate}), I_D = 14A \text{ pulsed}$$

Figure 13: Drain-Source Leakage Current


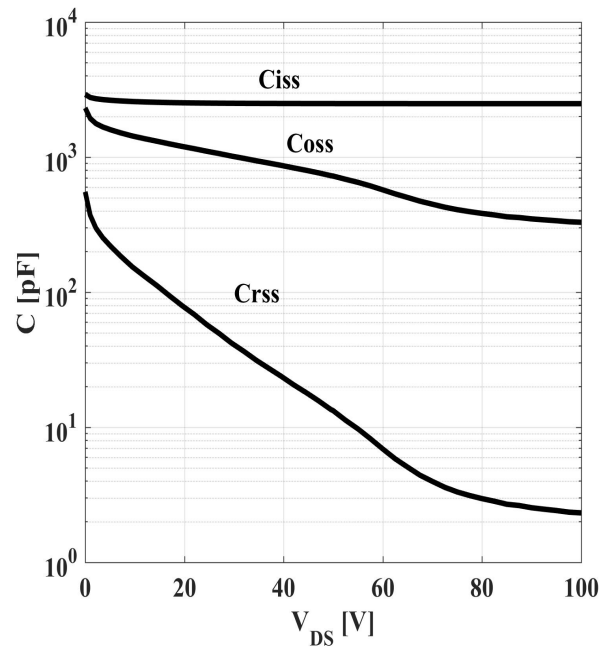
$$I_{DSS} = f(V_{DS}); V_{GS} = 0V; \text{parameter: } T_j$$

Figure 14: Forward Characteristics of Reverse Diode


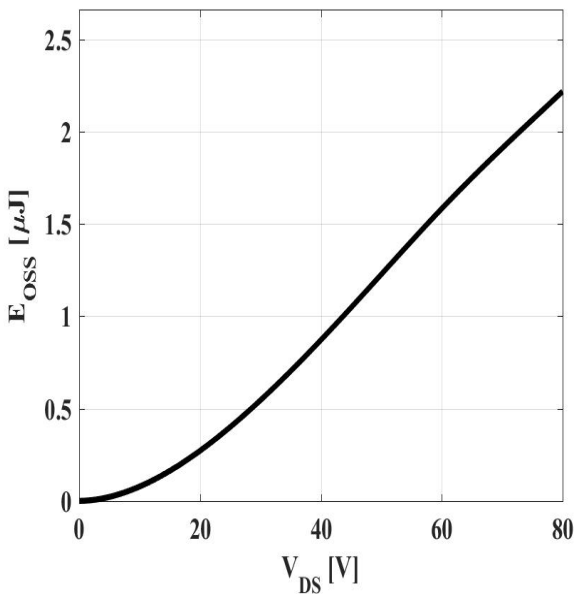
$$I_F = f(V_{SD}); \text{parameter: } T_j$$

Figure 15: Avalanche Energy


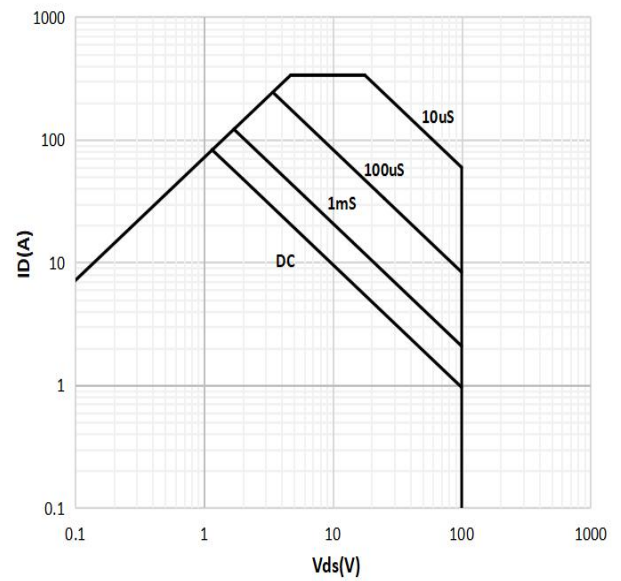
$$E_{AS}=f(T_j); I_D=14.0A; V_{DD}=50V$$

Figure 16: Typ. Capacitances


$$C=f(V_{DS}); V_{GS}=0; f=1MHz$$

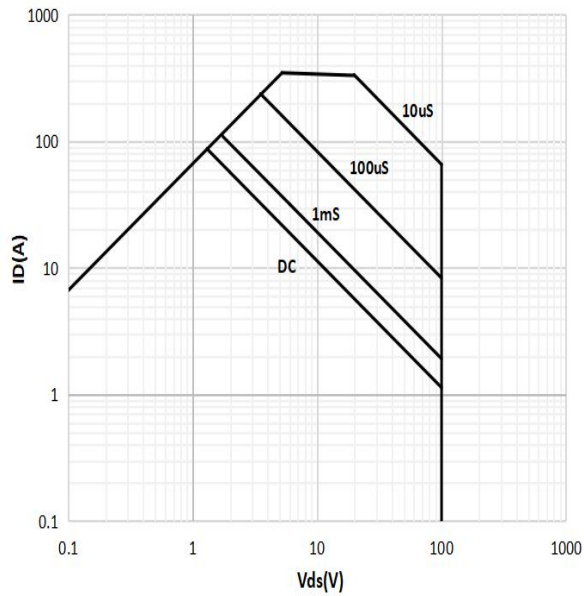
Figure 17: Coss Stored Energy


$$E_{OSS}=f(V_{DS})$$

Figure 18A: Safe Operating Area(PDFN5*6)


$$I_D = f(V_{DS}); T_c = 25^{\circ}C; V_{GS} > 7V; \text{parameter } t_p$$

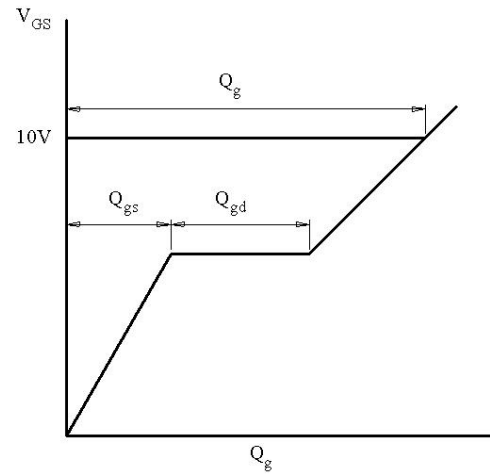
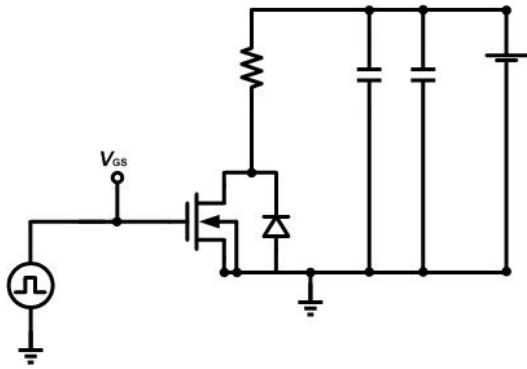
Figure 18B: Safe Operating Area(TO-220C)



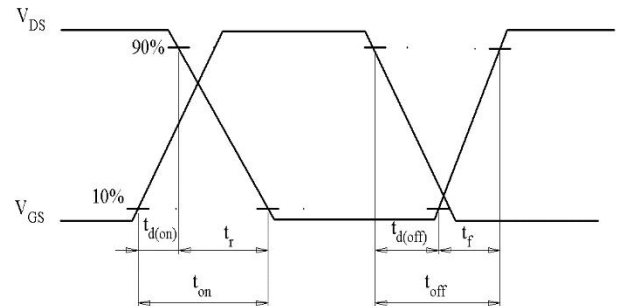
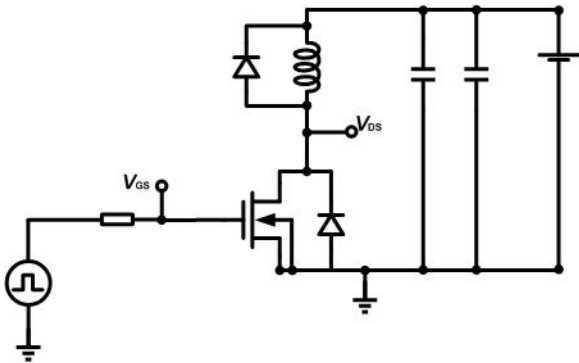
$I_D = f(V_{DS})$; $T_c = 25^\circ\text{C}$; $V_{GS} > 7\text{V}$; parameter t_p

Test Circuits

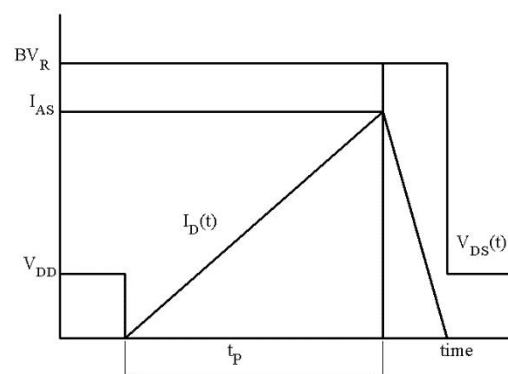
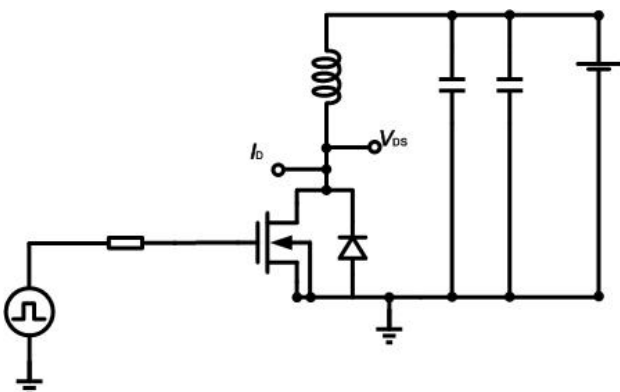
1. Gate Charge Test Circuit & Waveform



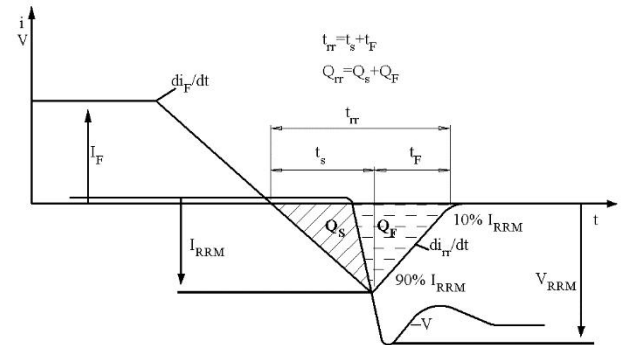
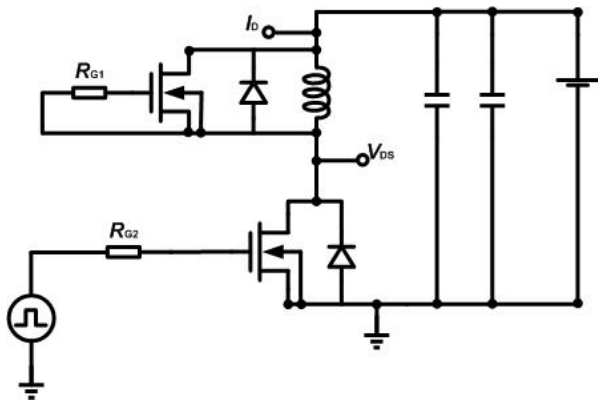
2. Switch Time Test Circuit

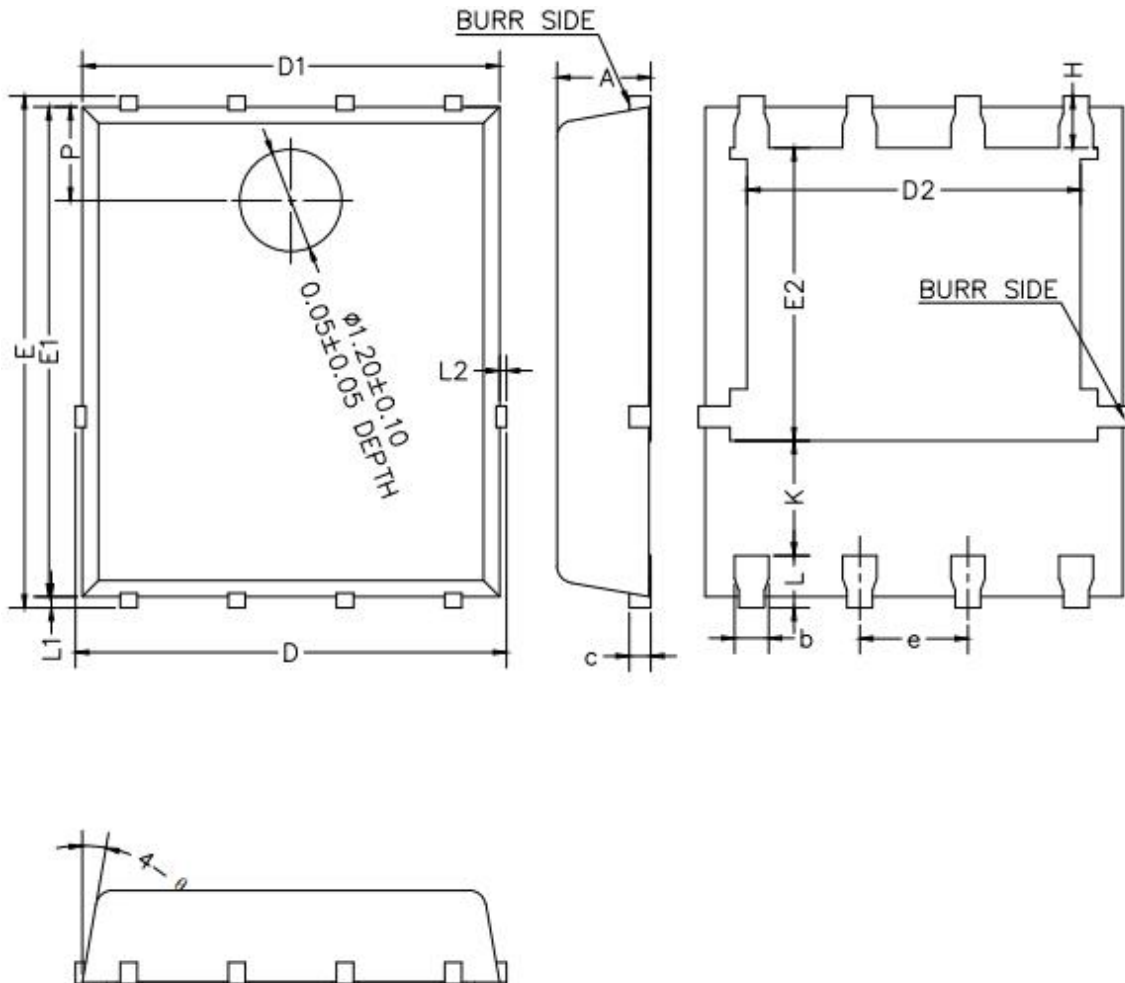


3. Unclamped Inductive Switching Test Circuit & Waveforms



4. Test Circuit and Waveform for Diode Characteristics



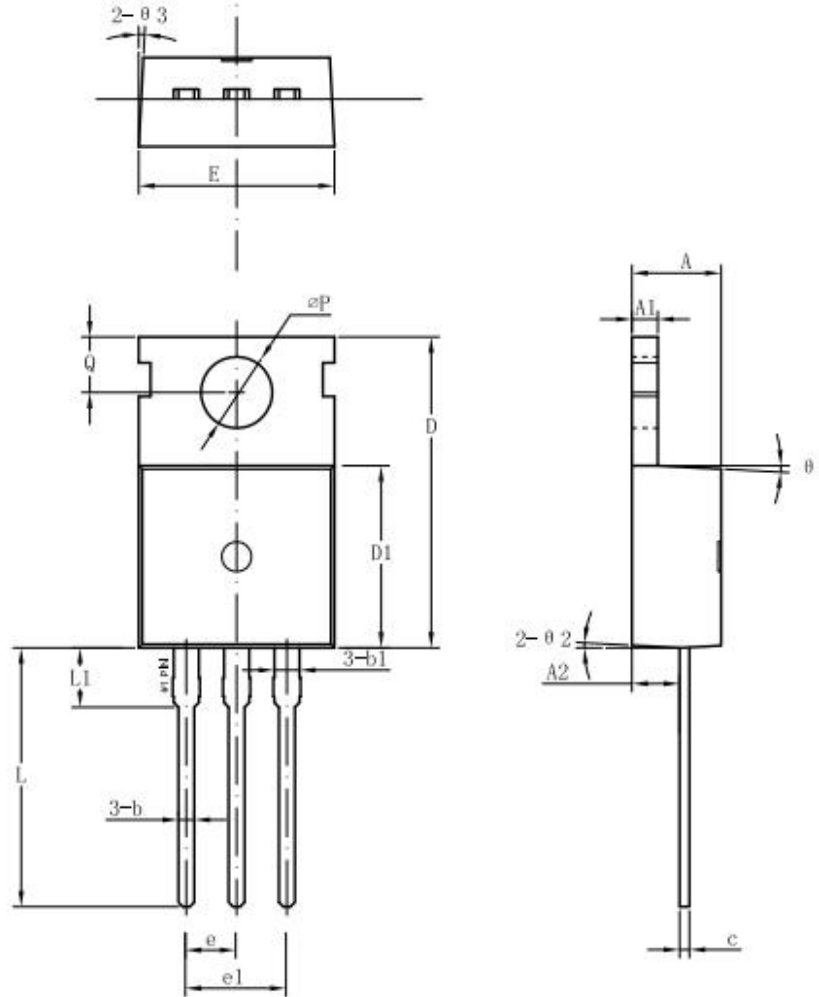
Mechanical Dimensions
DFN5*6-8 Unit: mm


Symbol	Dimensions (mm)			Symbol	Dimensions (mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.90	1.10	1.20	E2	3.18	—	3.54
b	0.35	0.40	0.45	H	0.51	0.61	0.71
c	0.21	0.25	0.34	K	1.10	—	—
D	—	—	5.10	L	0.51	0.61	0.71
D1	4.80	4.90	5.00	L1	0.06	0.13	0.20
D2	3.82	—	4.11	L2	—	—	0.10
e	1.17	1.27	1.37	P	1.00	1.10	1.20
E	5.90	6.00	6.10	θ	8°	10°	12°
E1	5.70	5.75	5.80				

Mechanical Dimensions

TO-220C(SRT10N022HTC-G/E)

Unit: mm



Symbol	Dimensions (mm)			Symbol	Dimensions (mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.30	4.50	4.70	e	—	2.54	—
A1	1.25	1.30	1.40	e1	—	5.08	—
A2	2.20	2.40	2.60	L	12.60	13.08	13.60
b	0.70	0.80	0.95	L1	—	3.00	—
b1	—	1.27	—	ΦP	3.50	3.60	3.80
c	0.40	0.50	0.65	Q	2.60	2.80	3.00
D	15.20	15.70	16.20	θ1	—	3°	—
D1	9.00	9.20	9.40	θ2	—	3°	—
E	9.70	10.00	10.10	θ3	—	3°	—



Sanrise Technology Limited Company

<http://www.sanrise-tech.com>

IMPORTANT NOTICE

Shenzhen Sanrise Technology Co., LTD. reserves the right to make changes without further notice to any products or specifications herein. Shenzhen Sanrise Technology Co., LTD. does not assume any responsibility for use of any its products for any particular purpose, nor does Shenzhen Sanrise Technology Co., LTD. assume any liability arising out of the application or use of any its products or circuits. Shenzhen Sanrise Technology Co., LTD. does not convey any license under its patent rights or other rights nor the rights of others.

Main Site:

- Headquarter

Shenzhen Sanrise Technology Co., LTD.

A1206, Skyworth building, No. 008, gaoxinnan 1st Road,
Gaoxin District, Yuehai street,, Nanshan District, ShenZhen,
P.R.China

Tel: +86-755-22953335

Fax: +86-755-22916878

- Shanghai Office

Sanrise Technology Limited Company

Rm.401, Building B, No. 666, Zhangheng Road,
Zhangjiang Hi-Tech Park, Shanghai, P.R.China

Tel: +86-21-68825918